ON Semiconductor®

Initial Product/Process Change Notification

Document # : IPCN22135X
Issue Date: 28 February 2018

Title of Change:	5-inch Production line closure at ON Semiconductor Niigata Co., Ltd., Japan (OSNC).
Proposed first ship date:	23 January 2020
Contact information:	Contact your local ON Semiconductor Sales Office or <Tetsuya.Fukushima@onsemi.com>
Samples:	Contact your local ON Semiconductor Sales Office.
Type of notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.
Change Part Identification:	Date Code
Change category:	☒ Wafer Fab Change ☐ Assembly Change ☐ Test Change ☐ Other ________________

Change Sub-Category(s):

☐ Manufacturing Site Change/Addition
☒ Manufacturing Process Change
☐ Material Change
☐ Product specific change
☐ Datasheet/Product Doc change
☐ Shipping/Packaging/Marking
☐ Other: ________________________

Sites Affected:	ON Semiconductor Sites: ON Niigata, Japan	External Foundry/Subcon Sites: None

Description and Purpose:

This Initial notification announces the 5-inch production line closure due to supply risk for 5-inch substrates from our wafer manufacturers as well constraints resulting from the aging of 5-inch production equipment.

The related products will be transferred to the same site ON Semiconductor Niigata Co., Ltd., Japan (OSNC) 6-inch production line.

Change Point	Before Change Description	After Change Description
Fab (OSNC)	N1 Fab (Minimum rule=0.8um, Class=100)	N1 Fab (Minimum rule=0.8um, Class=100) AND N2 Fab (Minimum rule=0.25um, Class=10)
Equipment	5inch equipment	6inch equipment (Each function is the same)
Si Sub material	5inch wafer	6inch wafer (No change except wafer diameter)

Qualification Plan:

QV DEVICE NAME: **LV8282PV-TLM-H**
PACKAGE: **SSOP44K (275 mil)**

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Tj=150°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
HAST	JESD22-A101	130°C, 85% RH, 18.8psig, bias	96 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig,	96 hrs
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	-
HBM	JS001	100pF,1.5kohm	-
CDM	JS002		-

List of Affected Standard Part:

Part Number	Qualification Vehicle
LV8282PV-TLM-H	LV8282PV-TLM-H